

JK-nSMD200L PPTC DEVICES

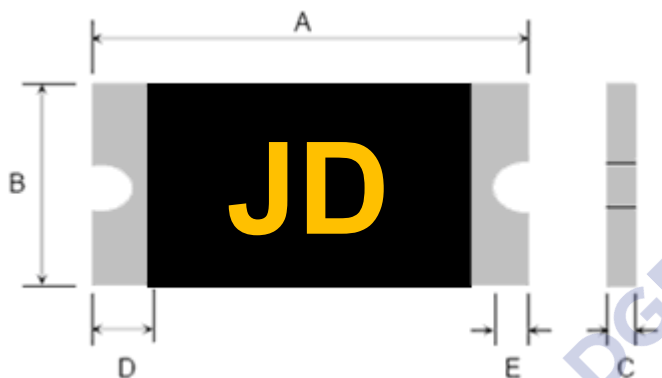
Part Number: Q/JKTD-12-200

Edition: A0

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金瑞电子材料
Jinrui Electronic material



Terminal pad materials : Tin-Plated Nickle-copper

Terminal pad solderability : Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.

Table1 :DIMENTION(Unit : mm)

Model	Marking	A		B		C		D	E
		Min.	Max.	Min.	Max.	Min.	Max	Min.	Min.
JK-nSMD200L	JD	3.0	3.5	1.5	1.8	0.3	0.7	0.15	0.1

Table2 :PERFORMANCE RATINGS:

Model	V _{MAX} (Vdc)	I _{MAX} (A)	I _H @25°C (A)	I _T @25°C (A)	P _D Typ (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	R _{iMIN} (Ω)	R _{lMAX} (Ω)
JK-nSMD200L	12.0	50.0	2.0	4.0	0.8	8.0	5.0	0.008	0.04

Table3:Test Conditons and Standards

Test Item	Test Conditons	Accept/Reject Criteria
Initial Resistance	In still air, 25°C	0.008-0.04Ω
Holding Current	25°C, 2.0A, 60min	No Trip
Time to Trip	25°C, 8.0A	≤5.0 S
Trip endurance	12V, 50.0A, 60min	No arcing or burning

Table4:Thermal Derating Chart-I_H (A)

Part number	Maximum ambient operating temperatures(°C)								
	-40	-20	0	25	40	50	60	70	85
JK-nSMD200L	2.68	2.33	2.15	2.00	1.66	1.49	1.37	1.15	0.80

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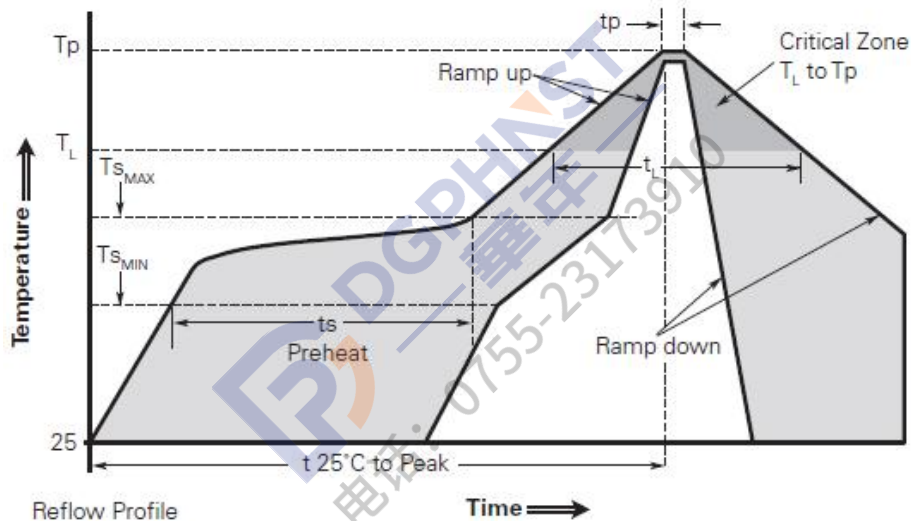
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Solder reflow conditions



Profile Feature	Pb-Free Assembly
Average ramp up rate (Ts_{MAX} to Tp)	3°C/second max.
Preheat	
• Temperature min. (Ts _{MIN})	150°C
• Temperature max. (Ts _{MAX})	200°C
• Time (ts _{MIN} to ts _{MAX})	60-120 seconds
Time maintained above:	
• Temperature (T _L)	217°C
• Time (t _L)	60-150 seconds
Peak/Classification temperature (Tp)	260°C
Time within 5°C of actual peak temperature	
Time (tp)	30 seconds max.
Ramp down rate	3°C/second max.
Time 25°C to peak temperature	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temperature profile meets RoHs leadfree process.

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

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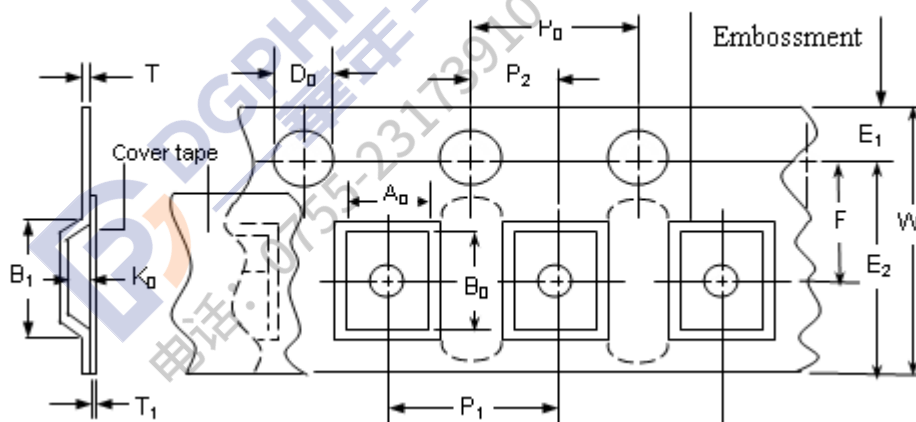


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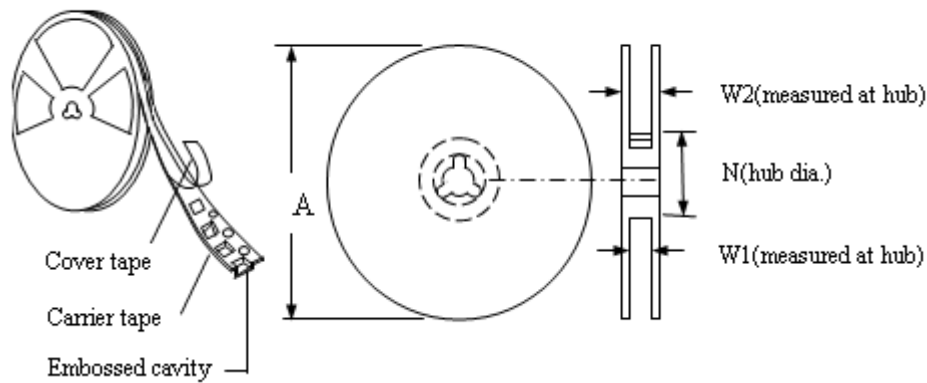
Tape and reel specifications (mm)

Covering Specifications EIA 481-1	
W	8.15+0.15/-0.3
P ₀	4.0 ± 0.10
P ₁	4.0 ± 0.10
P ₂	2.0 ± 0.05
A ₀	1.95 ± 0.10
B ₀	3.65 ± 0.10
D ₀	1.55 ± 0.05
F	3.50 ± 0.05
E ₁	1.75 ± 0.10
T	0.20 ± 0.10
Leader min.	390
Trailer min.	160
Reel Dimensions	
A	178 ± 1.0
N	59 ± 1
W ₁	8.5 ± 1.0 / -0.2
W ₂	12.0 ± 1

EIA Tape Component Dimensions



EIA Reel Dimensions



Operating Temperature: -40°C TO 85°C

Packaging: Bulk ,5000pcs per bag

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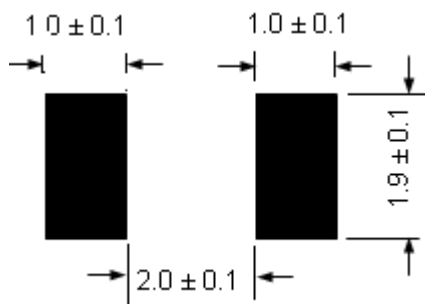
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Recommended pad layout (mm)



Storage

The maximum ambient temperature shall not exceed 38°C . Storage temperatures higher than 38°C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 60%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage ($L di/dt$) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices .PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.